



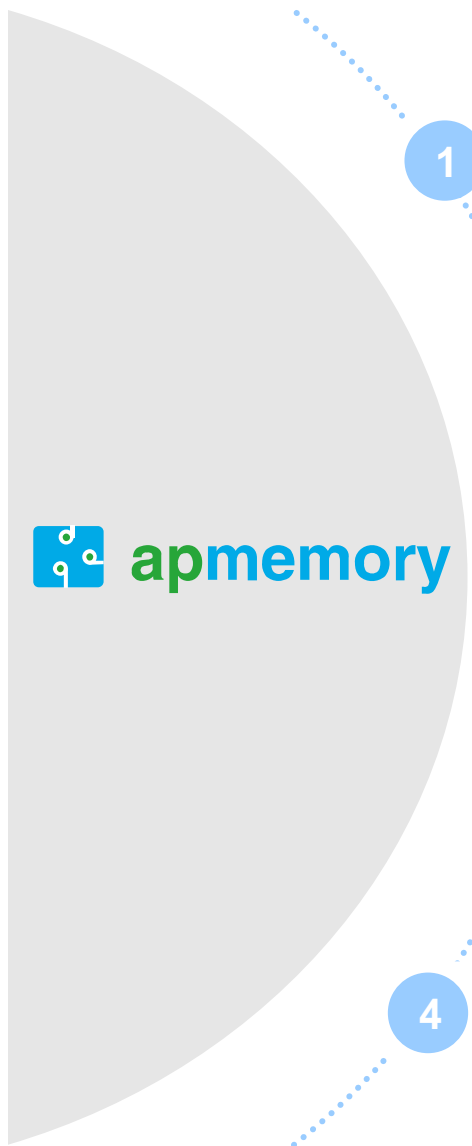
愛普科技股份有限公司 2023年第四季法人說明會

2024年3月5日

免責聲明

簡報中所提供對於產業及本公司前景之預測，係根據目前營運及公開資訊所做出之判斷，相關內容具風險與不確定性。任何外在環境的改變均可能影響公司實際營運與財務狀況，本簡報資料中所提供之資訊，不代表本公司對產業狀況或後續重大發展的完整論述，本公司亦不會因任何新的資訊或事件而更新相關資訊。

報告議程



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2023年第四季及2023年度財務報告

2023年第四季合併損益表

(in NT\$K)	4Q23		3Q23		4Q22		QoQ	YoY
營業收入	1,162,962	100%	1,239,550	100%	825,093	100%	(6%)	41%
營業毛利	509,036	44%	512,253	41%	352,693	43%	(1%)	44%
推銷費用	33,123	3%	31,288	3%	20,383	3%	6%	63%
管理費用	42,670	4%	41,329	3%	26,444	3%	3%	61%
研究發展費用	180,426	16%	160,229	13%	124,698	15%	13%	45%
預期信用減損損失(迴轉利益)	(30,716)	(3%)	18,839	1%	(109)	-	(263%)	(28,080%)
營業費用	225,503	20%	251,685	20%	171,416	21%	(10%)	32%
營業利益	283,533	24%	260,568	21%	181,277	22%	9%	56%
營業外收入	99,189	9%	388,872	31%	(98,587)	(12%)	(74%)	201%
稅前淨利	382,722	33%	649,440	52%	82,690	10%	(41%)	363%
所得稅費用	12,602	1%	119,844	9%	18,122	2%	(89%)	(30%)
本期淨利	370,120	32%	529,596	43%	64,568	8%	(30%)	473%
基本每股盈餘(NT\$)	\$2.29		\$3.27		\$0.40		(30%)	473%
加權平均股數(仟股)	161,936		161,869		161,512		0.04%	0.26%

2023年第四季合併損益表-擬制資訊

(in NT\$K)	4Q23		3Q23		4Q22		QoQ	YoY
營業收入	1,162,962	100%	1,239,550	100%	825,093	100%	(6%)	41%
營業毛利	509,036	44%	512,253	41%	352,693	43%	(1%)	44%
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預期信用減損損失(迴轉利益)	(30,716)	(3%)	18,839	1%	(109)	-	(263%)	(28,080%)
營業費用	225,503	20%	251,685	20%	171,416	21%	(10%)	32%
營業利益	283,533	24%	260,568	21%	181,277	22%	9%	56%
營業外收入*	386,839	34%	180,554	15%	94,751	12%	114%	308%
稅前淨利*	670,372	58%	441,122	36%	276,028	34%	52%	143%
所得稅費用*	70,132	6%	78,180	7%	56,790	7%	(10%)	23%
本期淨利*	600,240	52%	362,942	29%	219,238	27%	65%	174%
基本每股盈餘(NT\$)*	\$3.71		\$2.24		\$1.36		65%	173%
加權平均股數(仟股)	161,936		161,869		161,512		0.04%	0.26%

*排除GDR未支用資金所產生之兌換利益及所得稅影響數

2023年度合併損益表

(in NT\$K)	2023		2022		YoY
營業收入	4,226,907	100%	5,094,775	100%	(17%)
營業毛利	1,755,006	42%	2,221,394	44%	(21%)
推銷費用	124,811	3%	126,823	3%	(2%)
管理費用	164,854	4%	132,623	3%	24%
研究發展費用	583,627	14%	462,066	9%	26%
預期信用減損損失(迴轉利益)	28,933	1%	(638)	-	4,635%
營業費用	902,225	22%	720,874	15%	25%
營業利益	852,781	20%	1,500,520	29%	(43%)
營業外收入	766,200	18%	948,763	19%	(19%)
稅前淨利	1,618,981	38%	2,449,283	48%	(34%)
所得稅費用	174,011	4%	507,587	10%	(66%)
本期淨利	1,444,970	34%	1,941,696	38%	(26%)
基本每股盈餘(NT\$)	\$8.93		\$12.09		(26%)
加權平均股數(仟股)	161,847		160,602		0.78%

2023年度合併損益表-擬制資訊

(in NT\$K)	2023		2022		YoY
營業收入	4,226,907	100%	5,094,775	100%	(17%)
營業毛利	1,755,006	42%	2,221,394	44%	(21%)
推銷費用	124,811	3%	126,823	3%	(2%)
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營業費用	902,225	22%	720,874	15%	25%
營業利益	852,781	20%	1,500,520	29%	(43%)
營業外收入*	766,155	18%	379,945	8%	102%
稅前淨利*	1,618,936	38%	1,880,465	37%	(14%)
所得稅費用*	174,002	4%	393,824	8%	(56%)
本期淨利*	1,444,934	34%	1,486,641	29%	(3%)
基本每股盈餘(NT\$)*	\$8.93		\$9.26		(4%)
加權平均股數(仟股)	161,847		160,602		0.78%

*Exclude FX impact from the unused GDR proceeds.

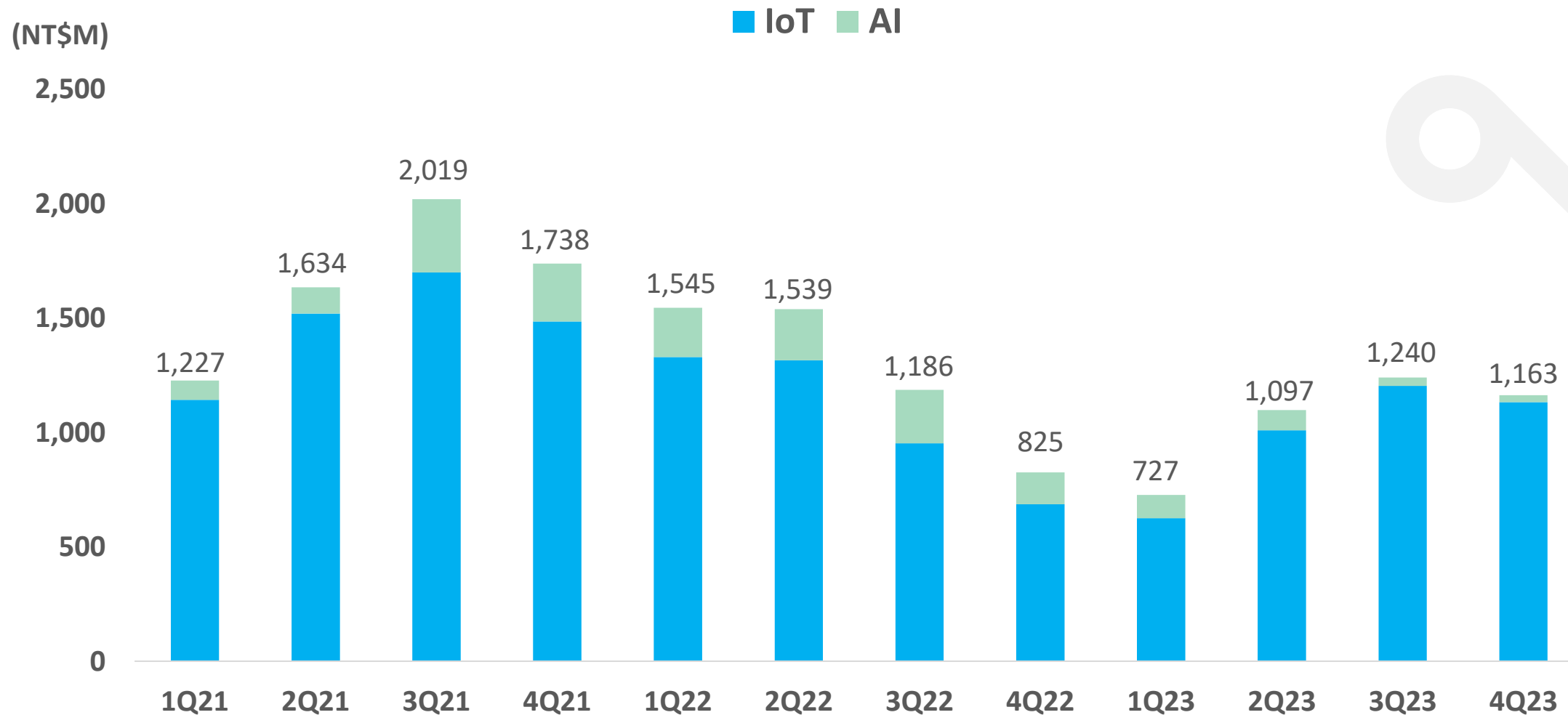
2023.12.31 合併資產負債表

(in NT\$K)	2023.12.31		2023.09.30		2022.12.31	
	AMT	%	AMT	%	AMT	%
資產總計	12,513,591	100%	11,741,570	100%	11,691,311	100%
現金及約當現金	8,864,216	71%	8,744,481	75%	8,182,432	70%
應收帳款	567,535	5%	755,236	6%	638,597	5%
存貨	851,330	7%	903,236	8%	1,528,392	13%
透過損益按公允價值衡量之金融資產	1,139,267	9%	258,982	2%	256,007	2%
其他資產	1,091,243	8%	1,079,635	9%	1,085,883	10%
負債總計	1,191,797	10%	808,114	7%	740,744	6%
短期借款	300,000	2%	-	-	-	-
合約負債	68,828	1%	13,695	0%	23,043	0%
應付帳款	255,186	2%	218,635	2%	149,961	1%
本期所得稅負債	238,365	2%	255,716	2%	295,101	3%
其他負債	329,418	3%	320,068	3%	272,639	2%
權益總計	11,321,794	90%	10,933,456	93%	10,950,567	94%
每股淨值(NT\$)	69.89		67.54		67.78	

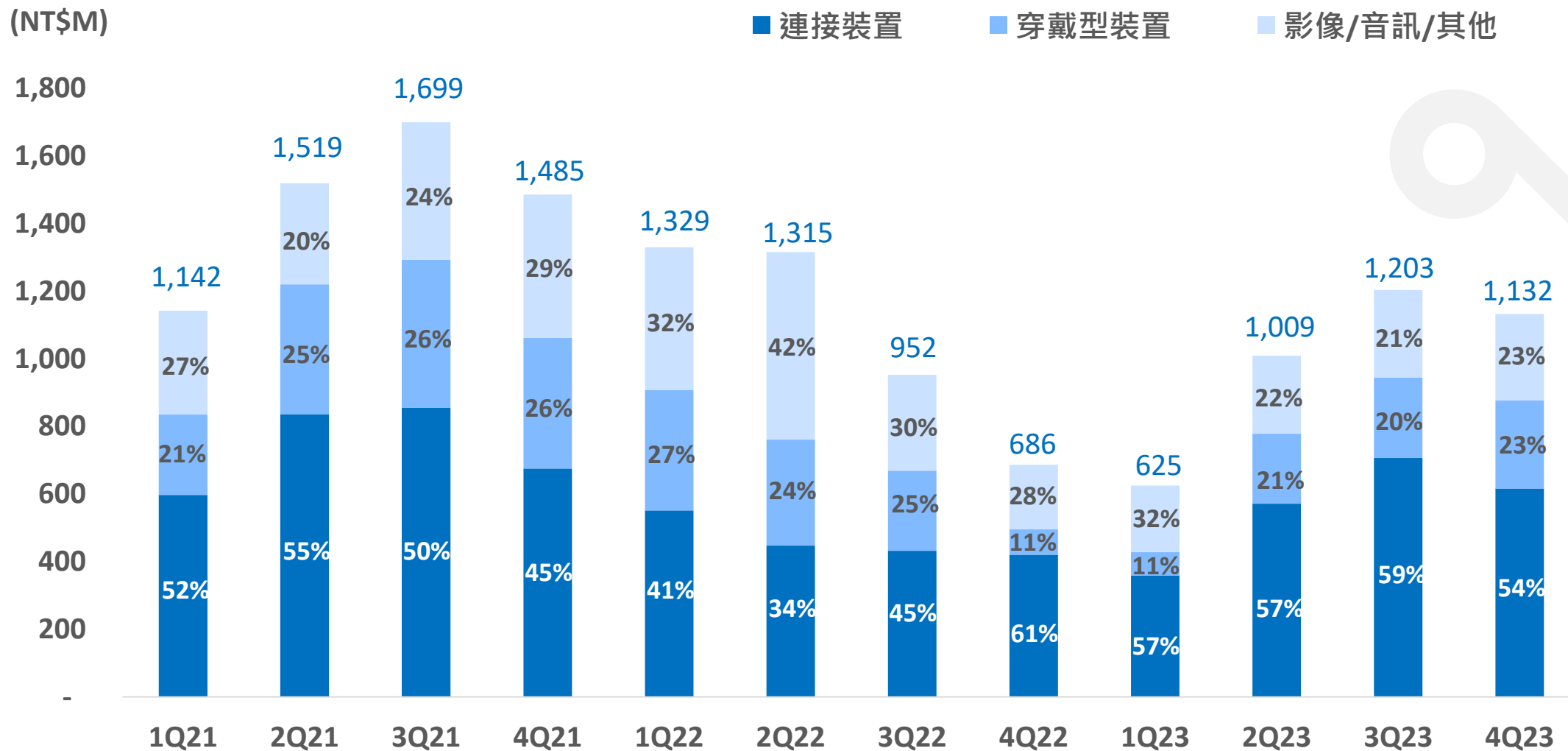
02

營運狀況

季度營收趨勢

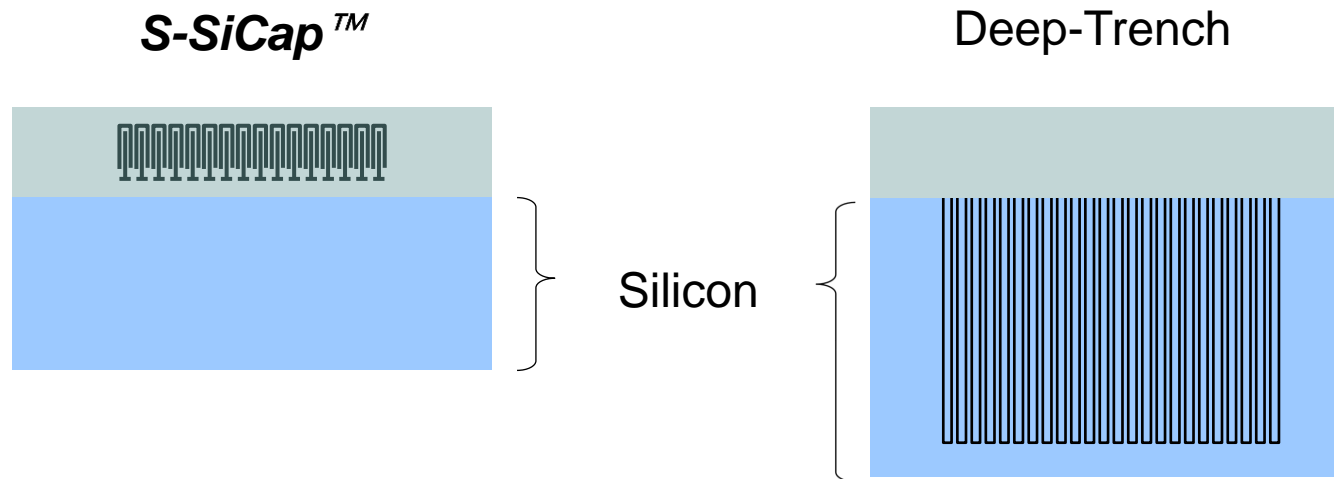


IoT 事業部 季營收



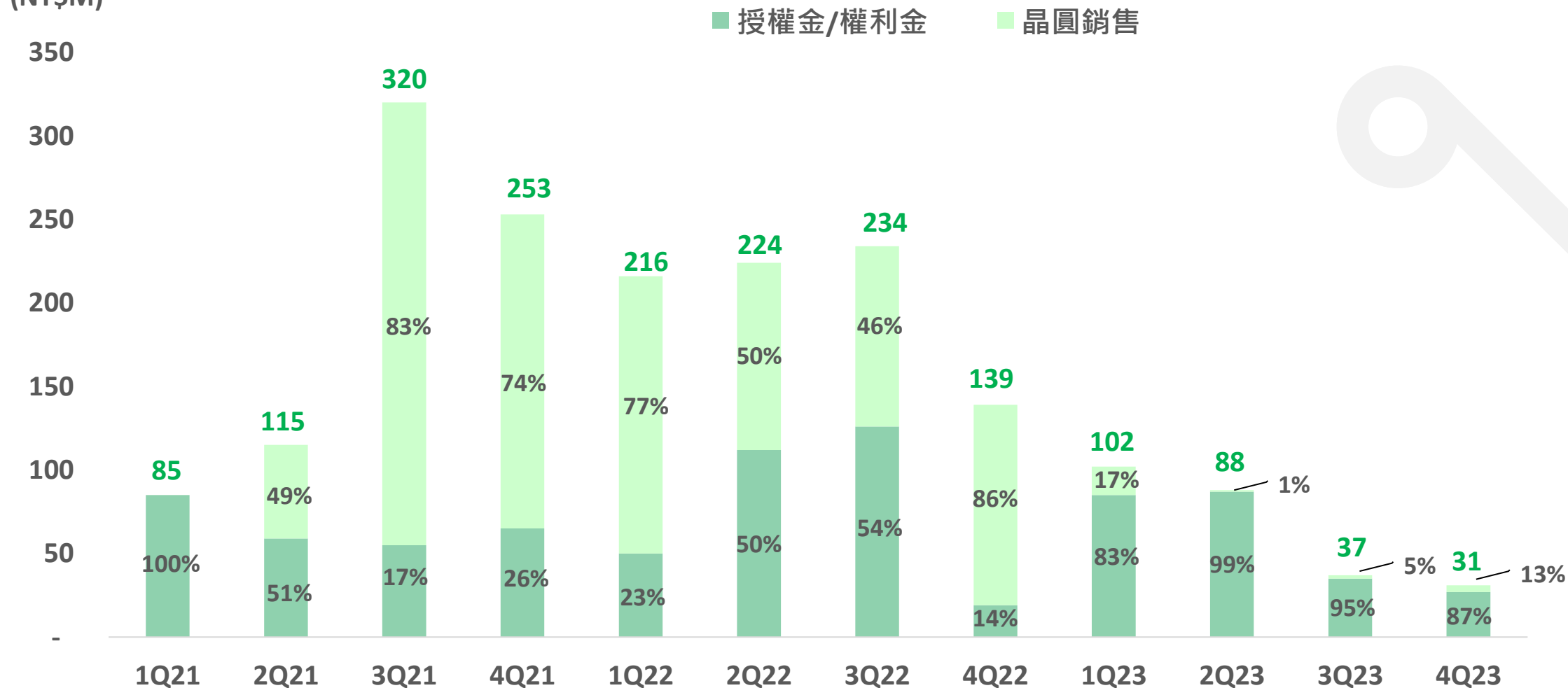
IPD: S-SiCap™ Technology

- S-SiCap™ (Stack Silicon Capacitor)
 - AP Memory's Silicon Capacitor technology which uses a stack capacitor
 - Offer higher capacitance density, smaller size, and thinner form factor



AI 事業部 季營收

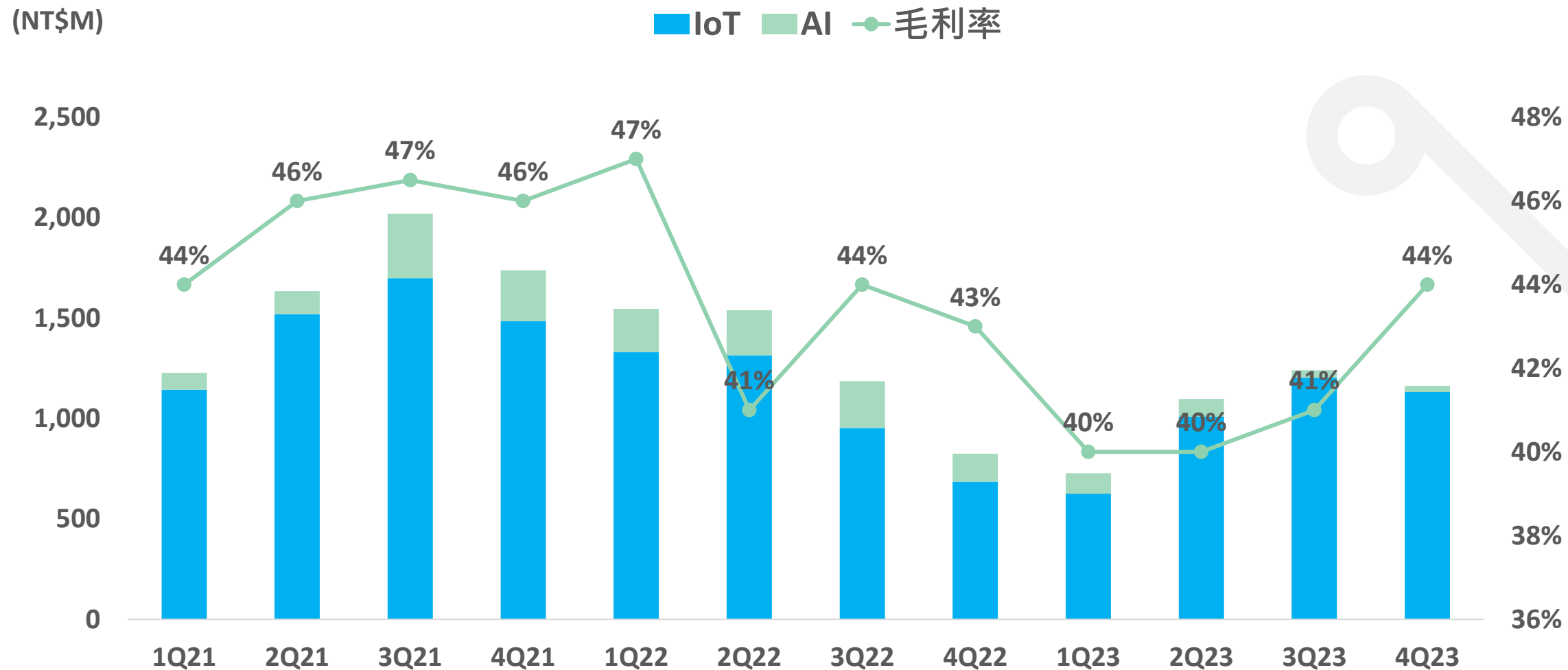
(NT\$M)



03

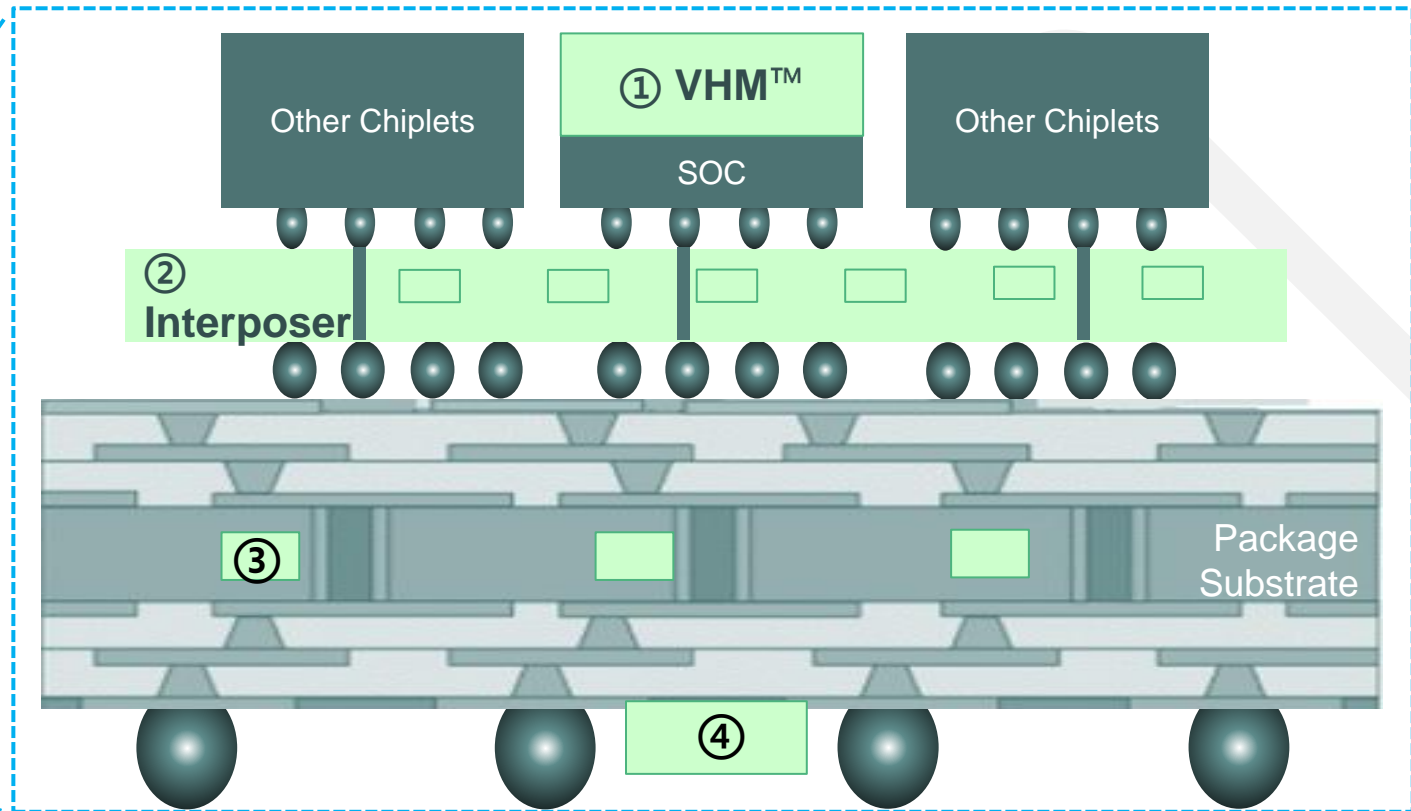
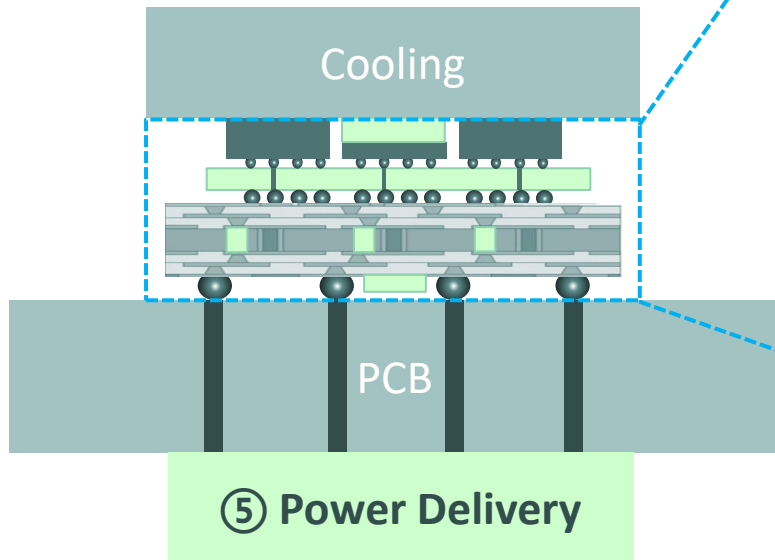
未來展望

營收與毛利率



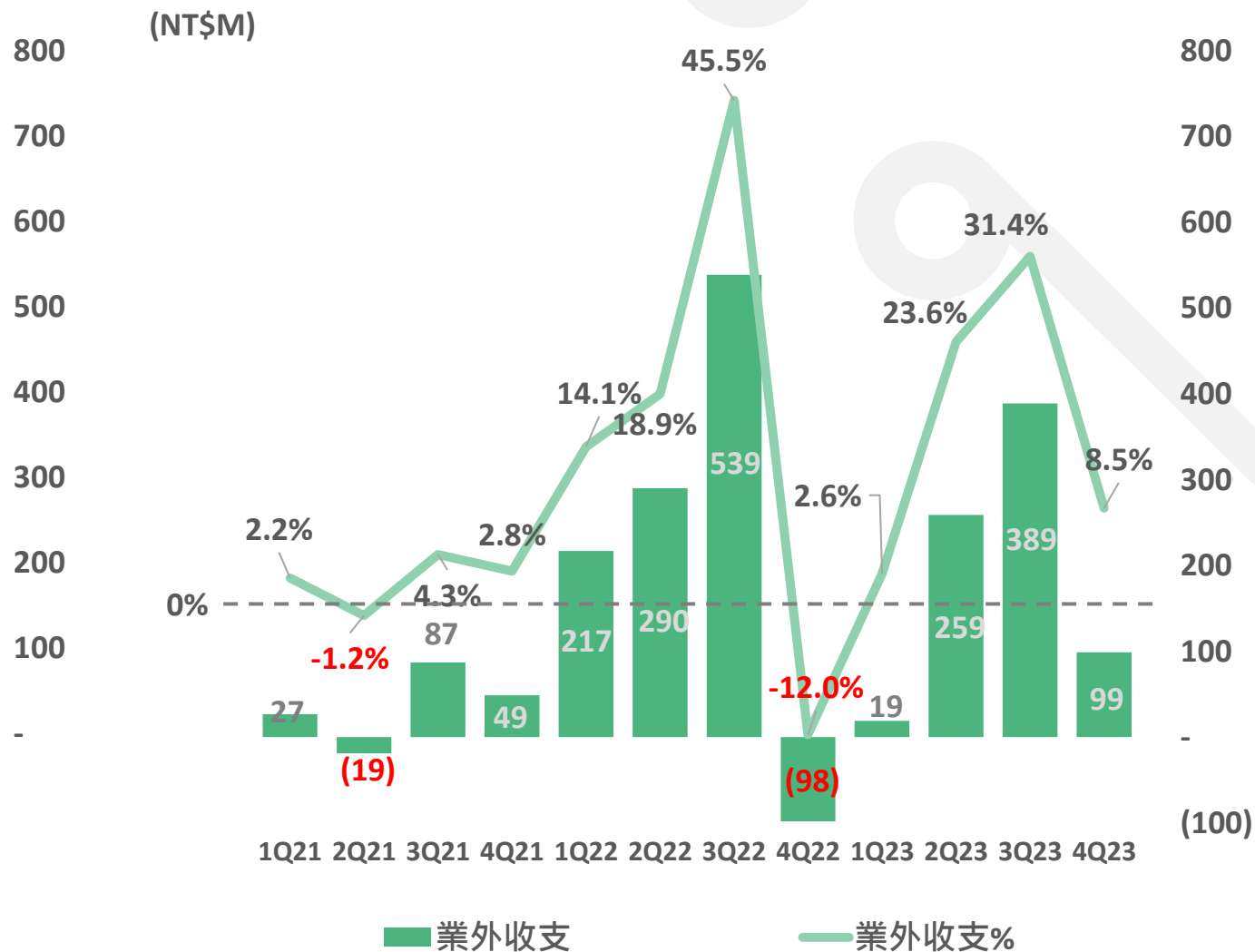
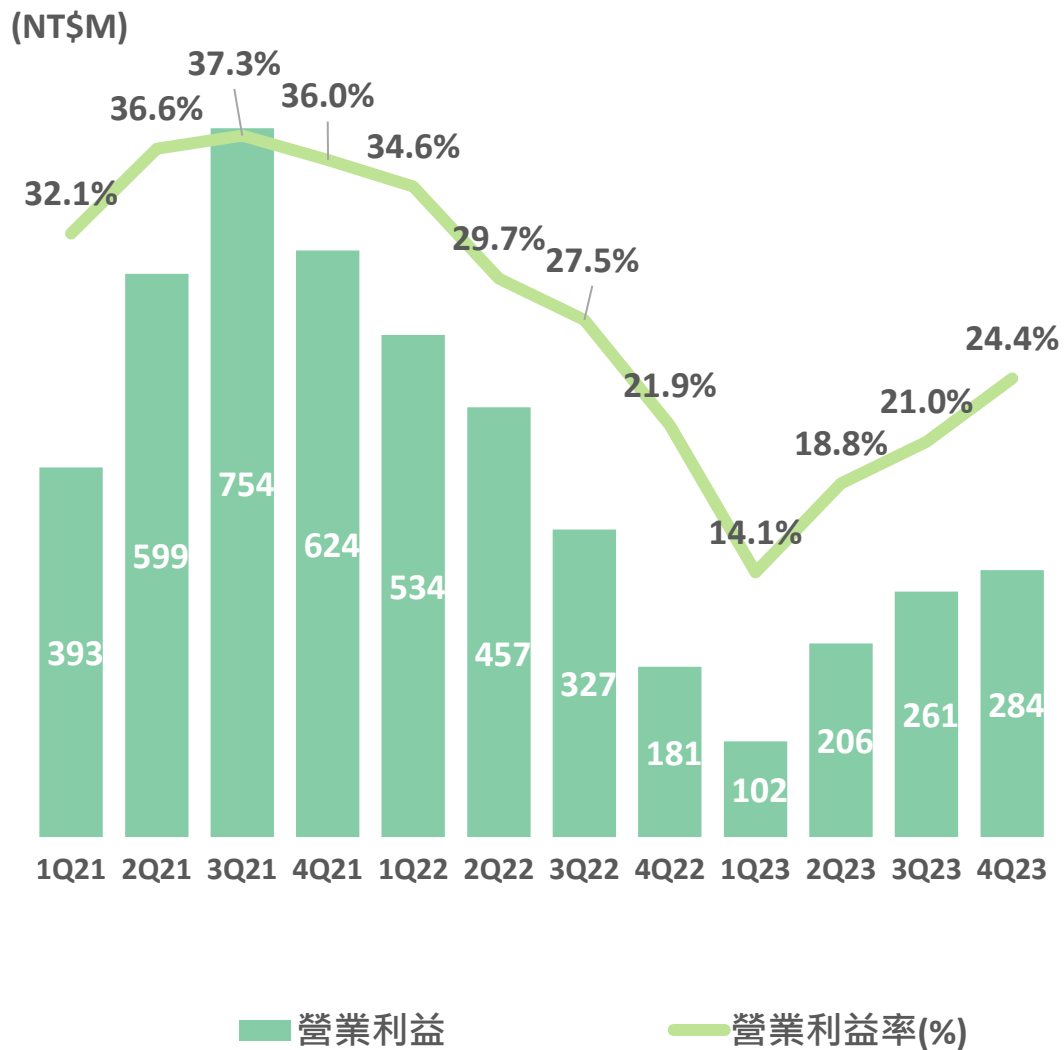
Positioning of AP Memory Solutions in AI/HPC

- ① VHM™ stacked with Compute
- ② Interposer with *S-SiCap™
- ③ S-SiCap™ embedded in Package Substrate
- ④ S-SiCap™ on landside
- ⑤ Power delivery solutions (future)



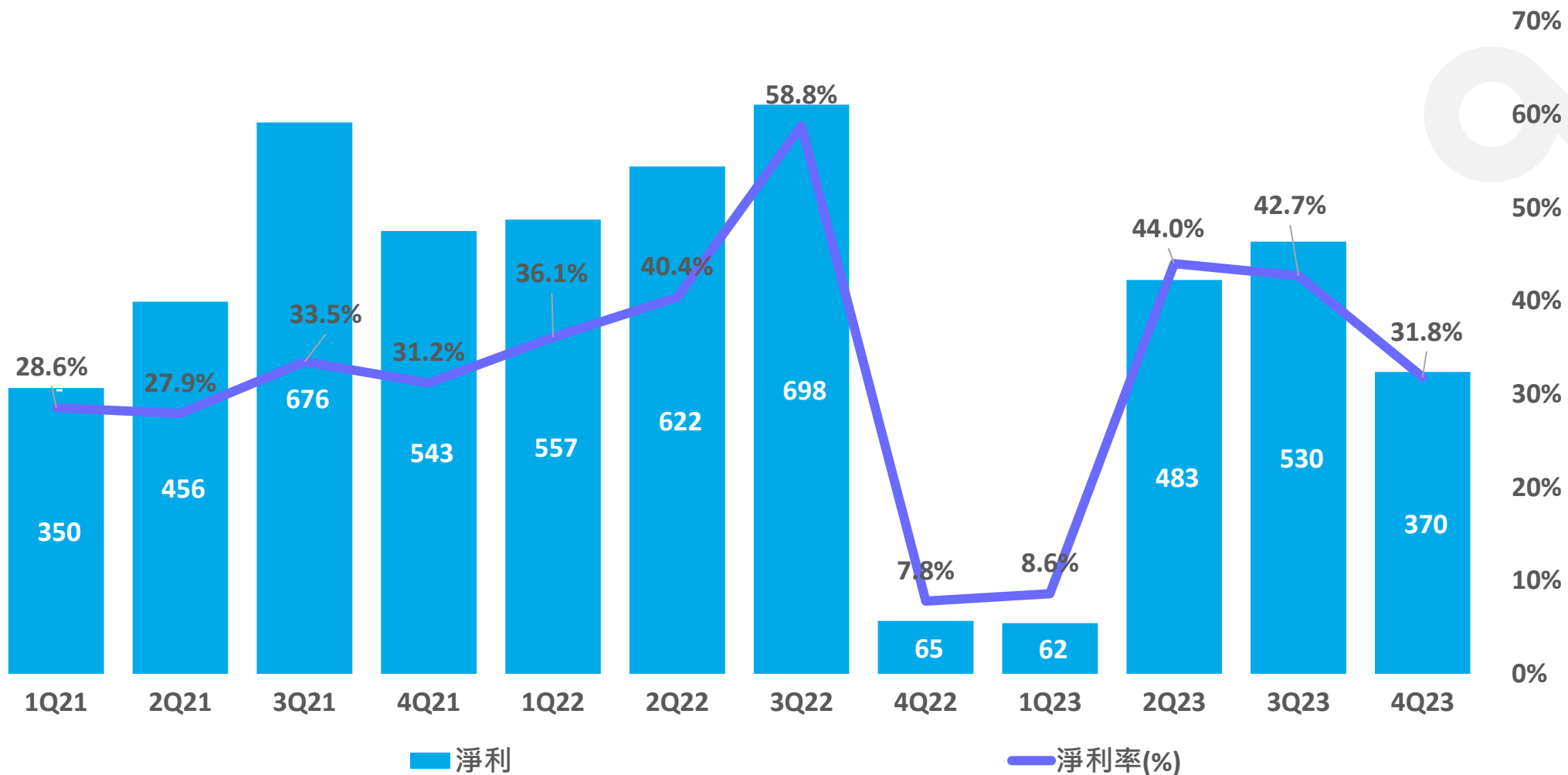
*S-SiCap™: Stack Silicon Capacitor, AP Memory's SiCap technology which uses a stack capacitor

營業利益及業外收支



淨利

(NT\$M)



未來展望

- **IoTRAM™**: 推出新的客製化介面
- **VHM™**: 預期2024年有更多概念驗證(POC)專案及 AI應用 design-in
- **Interposer with S-SiCap™**: 預期2024年有營收貢獻
- **S-SiCap™ embedded in Package Substrate**: 持續研究開發

Note: **S-SiCap™** - Stack Silicon Capacitor, AP Memory's SiCap technology which uses a stack capacitor
POC - Proof of Concept

Q&A

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